Diffusion

Diffusion - Mass transport by atomic motion

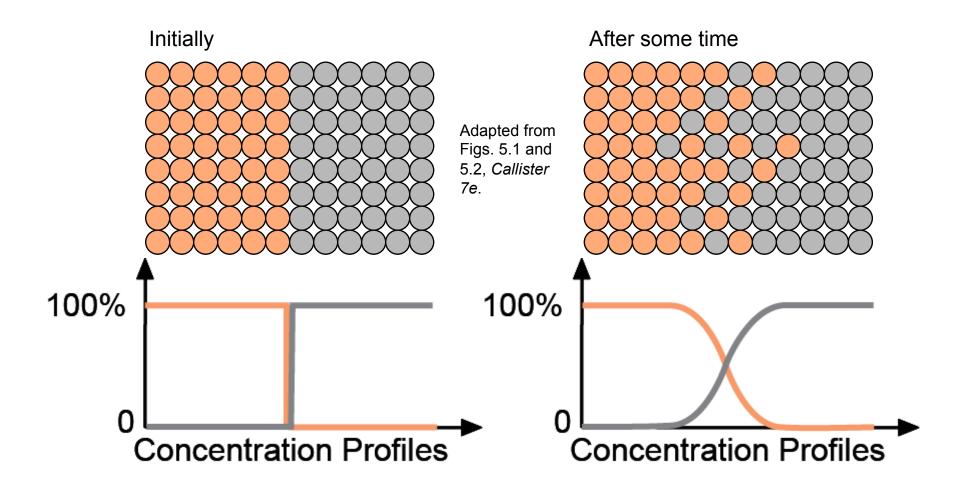
Mechanisms

- •Gases & Liquids random (Brownian) motion
- •Solids vacancy diffusion or interstitial diffusion

Interdiffusion: In an alloy, atoms tend to migrate from regions of high conc. to regions of low conc.

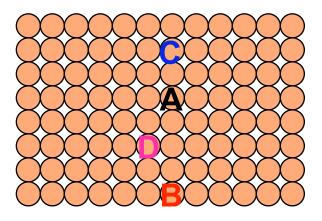
Self-diffusion: In an elemental solid, atoms also migrate.

Interdiffusion

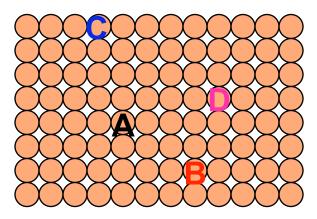


Self-diffusion

Label some atoms



After some time



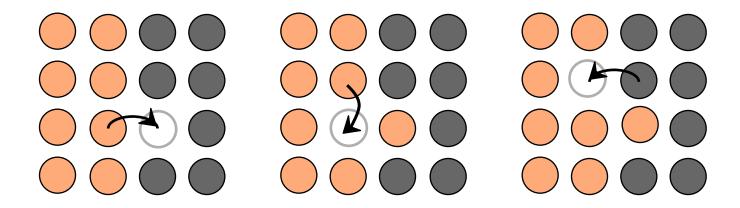
Diffusion mechanisms

Conditions:

- •There must be an empty site available
- Atoms must have the energy to make the jump

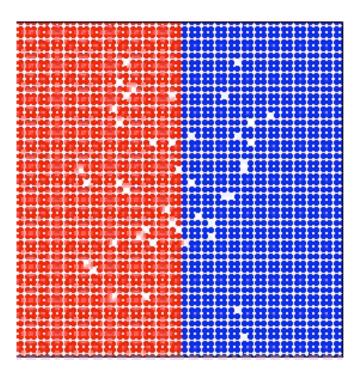
Vacancy Diffusion:

- atoms exchange with vacancies
- applies to substitutional impurities atoms
- rate depends on:
 - --number of vacancies
 - --activation energy to exchange.



Diffusion simulation

- Simulation of interdiffusion across an interface:
- Rate of substitutional diffusion depends on:
 - --vacancy concentration
 - --frequency of jumping.



(Courtesy P.M. Anderson)

Diffusion flux

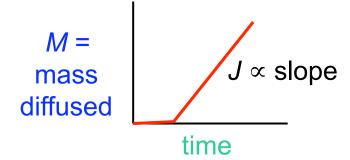
How do we quantify the amount or rate of diffusion?

$$J = \text{Flux} = \frac{\text{moles (or mass) diffusing}}{\text{(surface area)(time)}} = \frac{\text{mol}}{\text{cm}^2 \text{s}} \text{ or } \frac{\text{kg}}{\text{m}^2 \text{s}}$$

Measured empirically

- Make thin film (membrane) of known surface area
- Impose concentration gradient
- Measure how fast atoms or molecules diffuse through the membrane

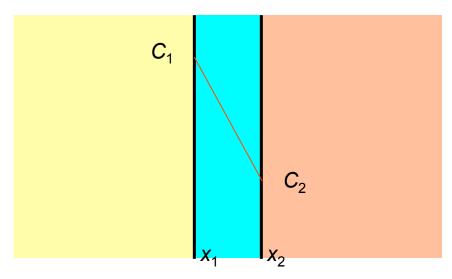
$$J = \frac{M}{At} = \frac{I}{A} \frac{dM}{dt}$$



Steady-state diffusion

Rate of diffusion independent of time

Flux proportional to concentration gradient =
$$\frac{dC}{dx}$$



if linear
$$\frac{dC}{dx} \cong \frac{\Delta C}{\Delta x} = \frac{C_2 - C_1}{x_2 - x_1}$$

Fick's first law of diffusion

$$J = -D\frac{dC}{dx}$$

D = diffusion coefficient

Diffusion and temperature

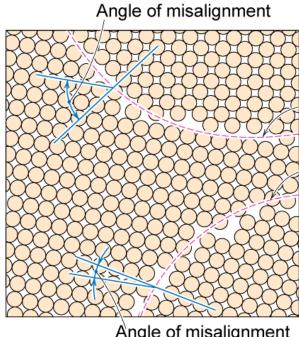
• Diffusion coefficient increases with increasing *T*.

$$D = D_o \exp \left(-\frac{Q_d}{RT}\right)$$

- D = diffusion coefficient [m²/s]
- D_0 = pre-exponential [m²/s]
- Q_d = activation energy [J/mol or eV/atom]
- R = gas constant [8.314 J/mol-K]
- τ = absolute temperature [K]

Diffusion paths





High-angle grain boundary

Small-angle grain boundary

Angle of misalignment

Diffusion FASTER for...

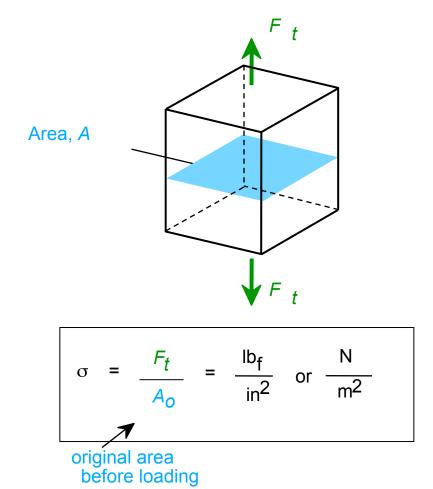
- open crystal structures
- materials w/secondary bonding
- smaller diffusing atoms
- lower density materials

Diffusion SLOWER for...

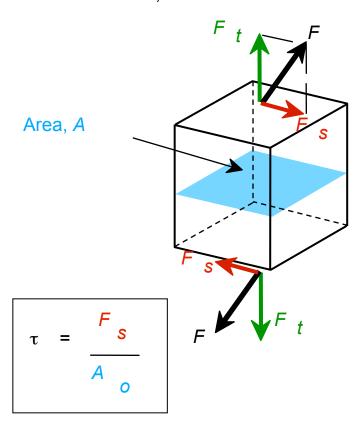
- close-packed structures
- materials w/covalent bonding
- larger diffusing atoms
- higher density materials

Engineering stress

• Tensile stress, σ :



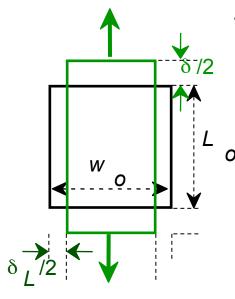
• Shear stress, τ :



Engineering strain

• Tensile strain:

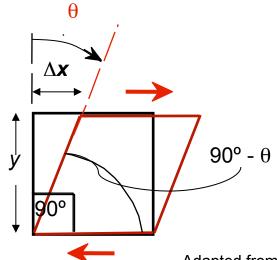
$$\varepsilon = \frac{\delta}{L_o}$$



• Lateral strain:

$$\varepsilon_L = \frac{-\delta_L}{W_O}$$

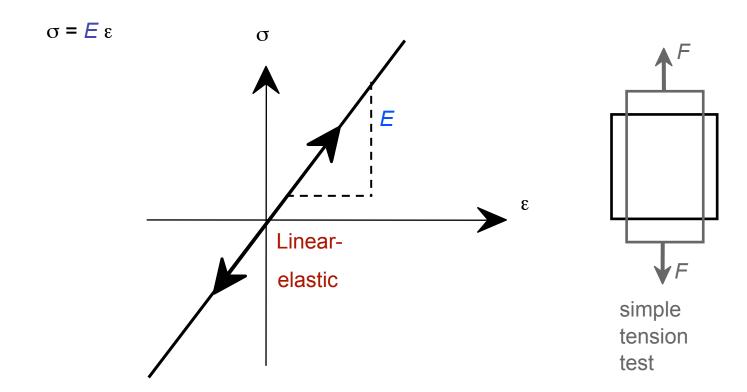
• Shear strain:



$$\gamma = \Delta x/y = \tan \theta$$

Engineering strain

- Modulus of Elasticity, E: (also known as Young's modulus)
- Hooke's Law:



Elastic properties of materials

• Poisson's ratio, v:

$$\mathbf{v} = -\frac{\varepsilon_L}{\varepsilon}$$

metals: $v \sim 0.33$

ceramics: $v \sim 0.25$

polymers: $v \sim 0.40$

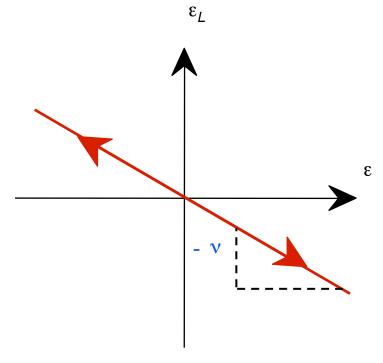
Units:

E: [GPa] or [psi]

v: dimensionless

-For *isotropic* materials

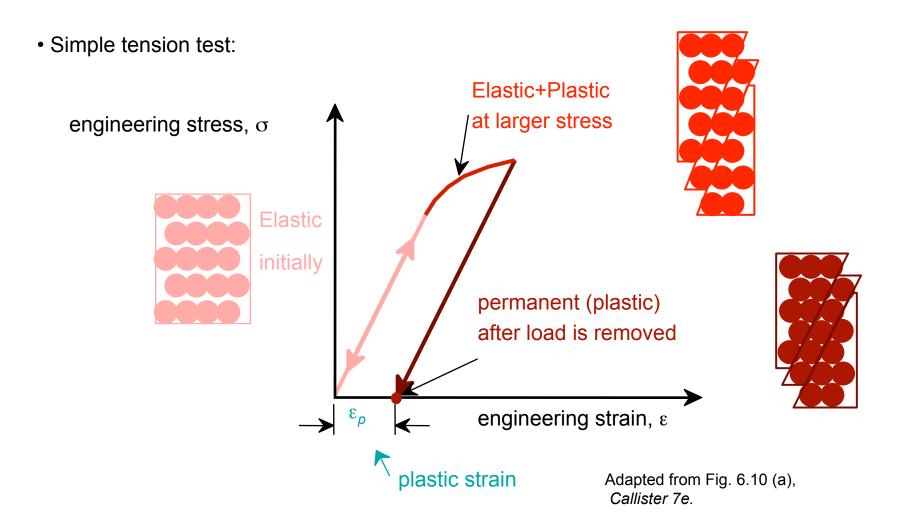
$$E = 2G (1+v)$$



-v > 0.50 density increases

-v < 0.50 density decreases (voids form)

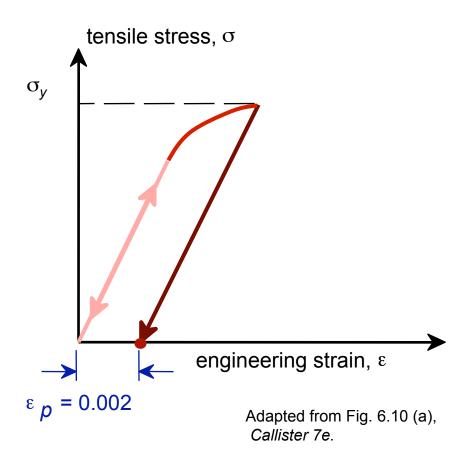
Plastic deformation



Yield strength, σ_{v}

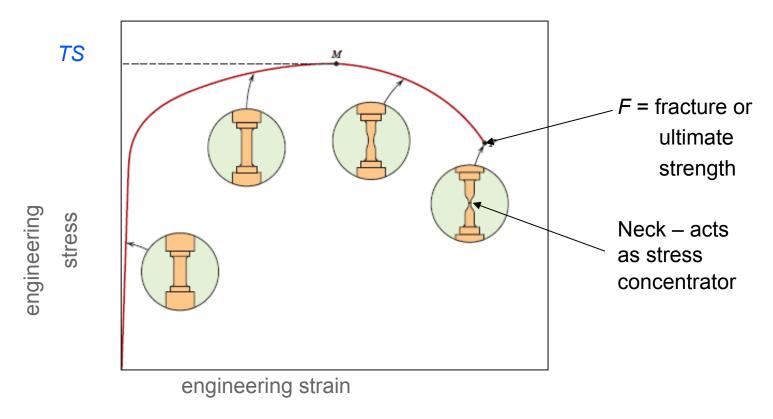
• Stress at which noticeable plastic deformation has occurred.





Tensile strength, TS

• Maximum stress on engineering stress-strain curve.



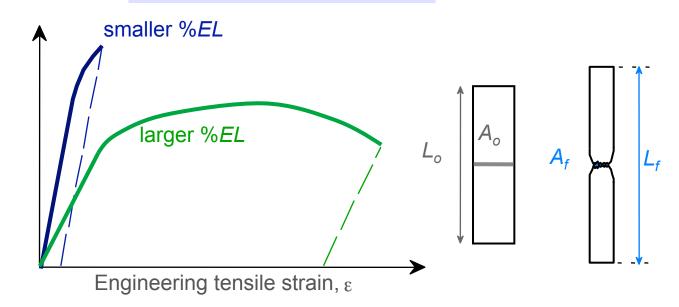
- Metals: occurs when noticeable necking starts.
- Polymers: occurs when polymer backbone chains are aligned and about to break.

Ductility

• Plastic tensile strain at failure:
$$\% EL = \frac{L_f - L_o}{L_o} \times 100$$

Engineering tensile stress, σ

Adapted from Fig. 6.13, Callister 7e.

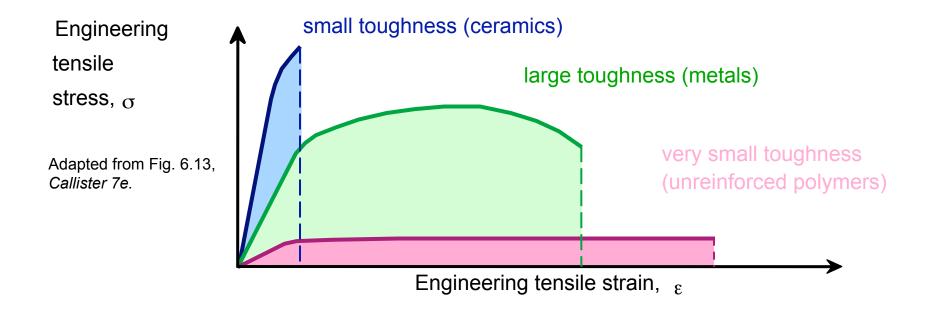


• Another ductility measure:

$$% RA = \frac{A_o - A_f}{A_o} \times 100$$

Toughness

- Energy to break a unit volume of material
- Approximate by the area under the stress-strain curve.

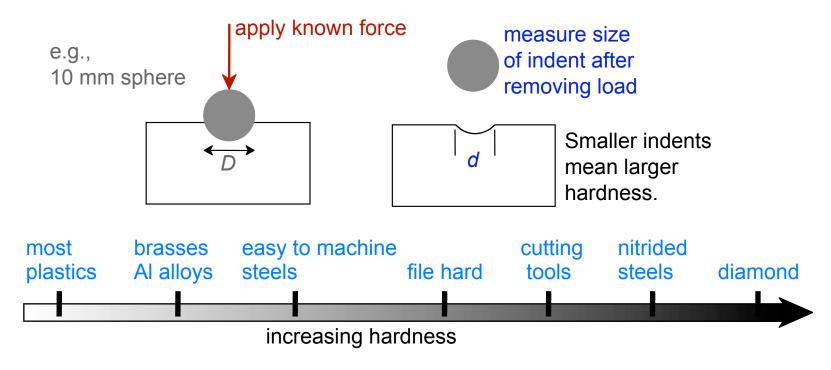


Brittle fracture: elastic energy

Ductile fracture: elastic + plastic energy

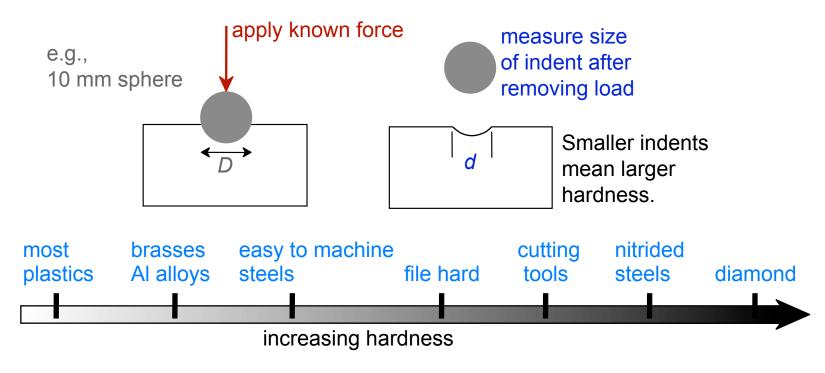
Hardness

- Resistance to permanently indenting the surface.
- Large hardness means:
 - --resistance to plastic deformation or cracking in compression.
 - --better wear properties.



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Hardness Measurement

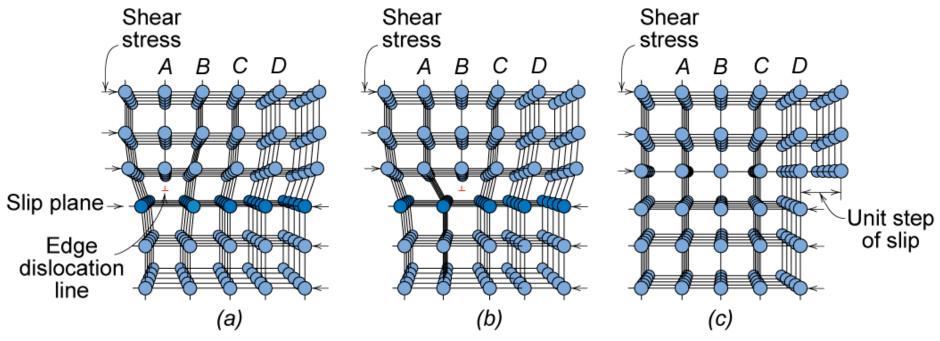
Table 6.5 Hardness Testing Techniques

Test	Indenter	Shape of Indentation			Formula for
		Side View	Top View	Load	Hardness Numbera
Brinell	10-mm sphere of steel or tungsten carbide	→ D ← d ←	<u></u> d ←	P	$HB = \frac{2P}{\pi D[D - \sqrt{D^2 - d^2}]}$
Vickers microhardness	Diamond pyramid	136°	d_1 d_1	P	$HV = 1.854P/d_1^2$
Knoop microhardness	Diamond pyramid	<i>l/b</i> = 7.11 <i>b/t</i> = 4.00	- l	P	$HK = 14.2P/l^2$
Rockwell and Superficial Rockwell	$\begin{cases} \text{Diamond} \\ \text{cone} \\ \frac{1}{16}, \frac{1}{8}, \frac{1}{4}, \frac{1}{2} \text{ in.} \\ \text{diameter} \\ \text{steel spheres} \end{cases}$	120°		100 150 15 30	kg kg kg Rockwell kg kg Superficial Rockwell kg

^a For the hardness formulas given, P (the applied load) is in kg, while D, d, d₁, and l are all in mm.
Source: Adapted from H. W. Hayden, W. G. Moffatt, and J. Wulff, The Structure and Properties of Materials, Vol. III, Mechanical Behavior. Copyright © 1965 by John Wiley & Sons, New York. Reprinted by permission of John Wiley & Sons, Inc.

Dislocation and plastic deformation

 Cubic & hexagonal metals - plastic deformation by plastic shear or slip where one plane of atoms slides over adjacent plane by defect motion (dislocations).

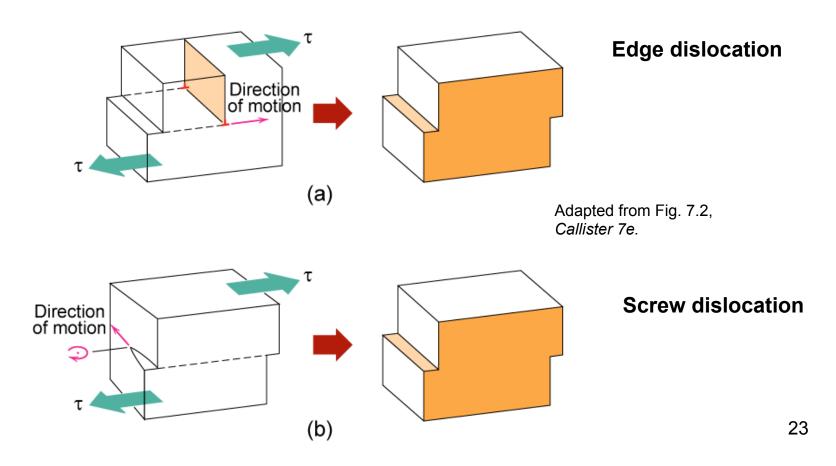


• If dislocations don't move, deformation doesn't occur!

Adapted from Fig. 7.1, *Callister 7e.*

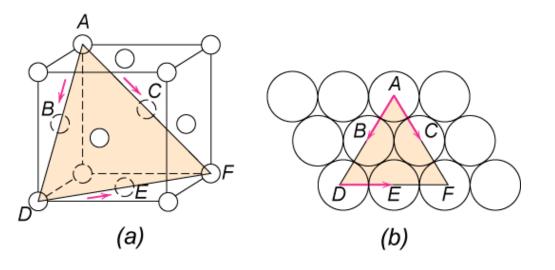
Dislocation motion

- Dislocation moves along slip plane in slip direction perpendicular to dislocation line
- Edge dislocations move parallel to the applied force, screw dislocations move perpendicular to the applied force



Deformation mechanisms

- Slip System
 - Slip plane plane allowing easiest slippage
 - Slip direction direction of movement

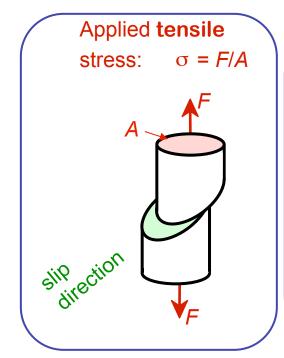


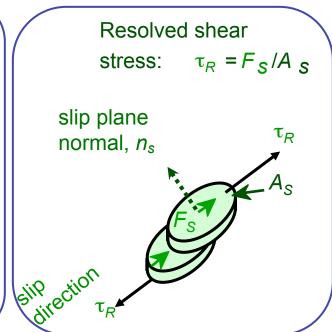
Adapted from Fig. 7.6, *Callister 7e.*

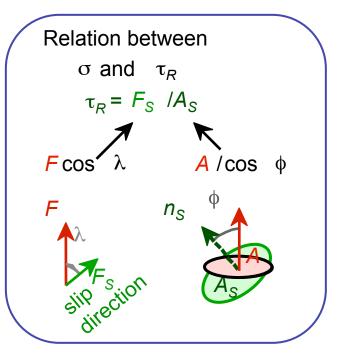
- FCC Slip occurs on {111} planes (close-packed) in <110> directions (close-packed)
 - => total of 12 slip systems in FCC

Slip in single crystals

- Crystals slip due to a resolved shear stress, τ_R .
- Applied tension can produce such a stress.







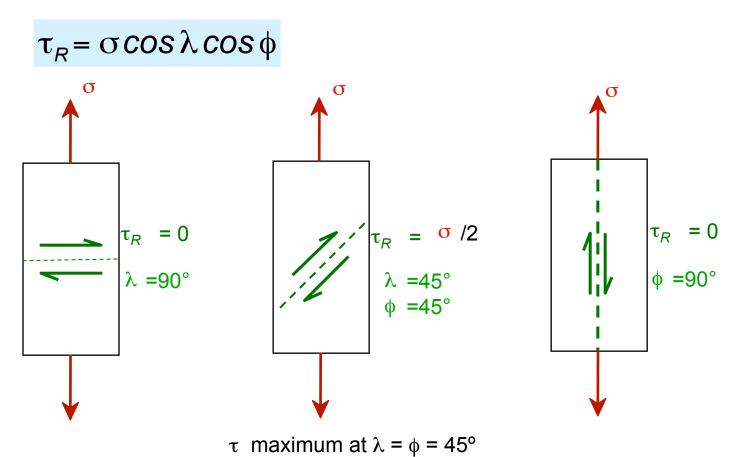
$$\tau_R = \sigma \cos \lambda \cos \phi$$

Critical resolved shear stress

• Condition for dislocation motion: $\tau_R > \tau_{CRSS}$

$$\tau_R > \tau_{CRSS}$$

• Crystal orientation can make it easy or hard to move dislocation



Slip motion in polycrystals

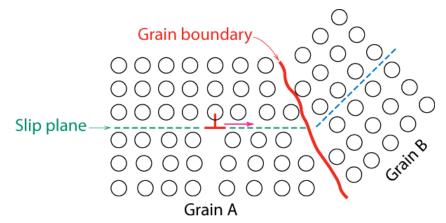
- Stronger grain boundaries pin deformations
- Slip planes & directions (λ, ϕ) change from one crystal to another.
- τ_R will vary from one crystal to another.
- The crystal with the largest τ_R yields first.
- Other (less favorably oriented) crystals yield later.



Adapted from Fig. 7.10, Callister 7e. (Fig. 7.10 is courtesy of C. Brady, National Bureau of Standards [now the National Institute of Standards and Technology, Gaithersburg, MD].)

Strategies for strengthening: grain size reduction

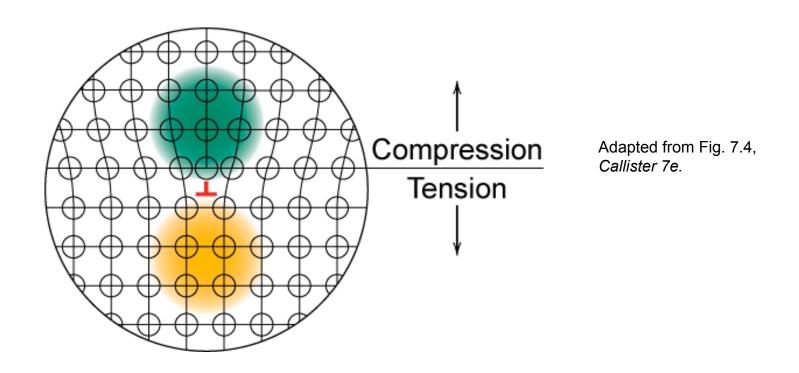
- Grain boundaries are barriers to slip.
- Barrier "strength" increases with increasing angle of misorientation.
- Smaller grain size: more barriers to slip.



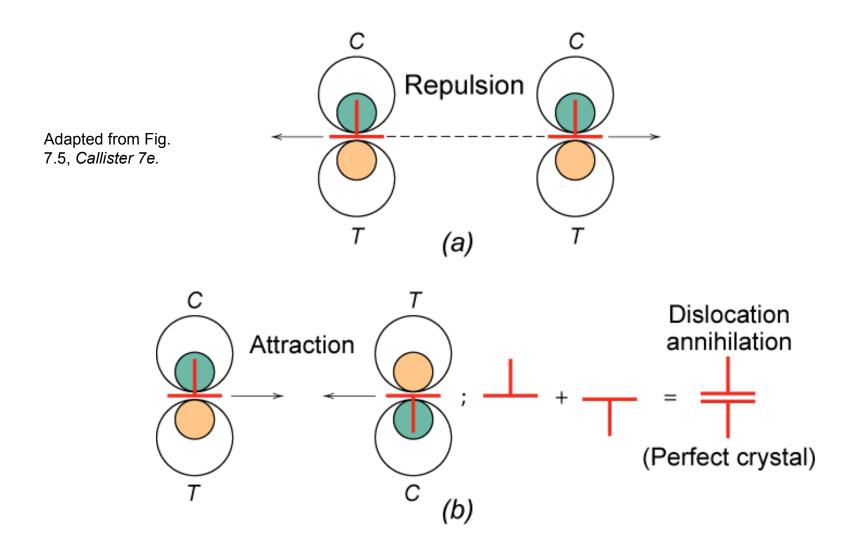
Adapted from Fig. 7.14, *Callister 7e.* (Fig. 7.14 is from *A Textbook of Materials Technology*, by Van Vlack, Pearson Education, Inc., Upper Saddle River, NJ.)

• Hall-Petch Equation:
$$\sigma_{yield} = \sigma_o + k_y d^{-1/2}$$

Strategies for strengthening: solid solutions

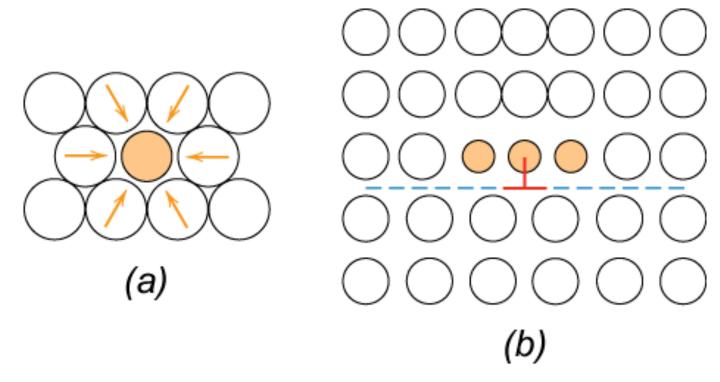


Effects of stress at dislocations



Strengthening by alloying

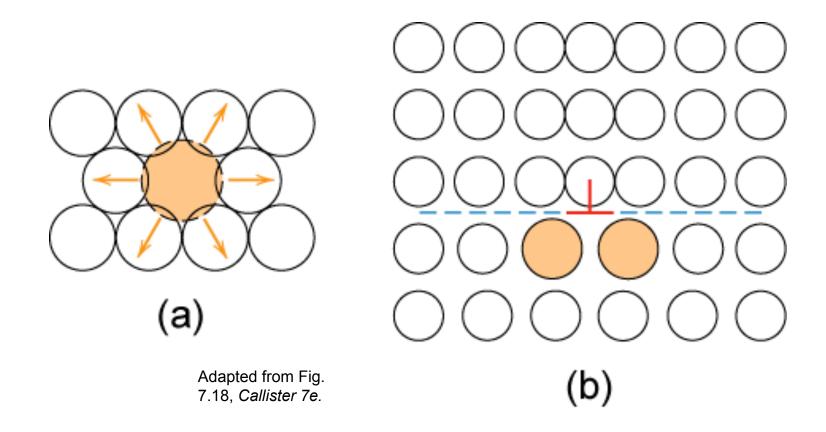
- small impurities tend to concentrate at dislocations
- reduce mobility of dislocation ∴ increase strength



Adapted from Fig. 7.17, Callister 7e.

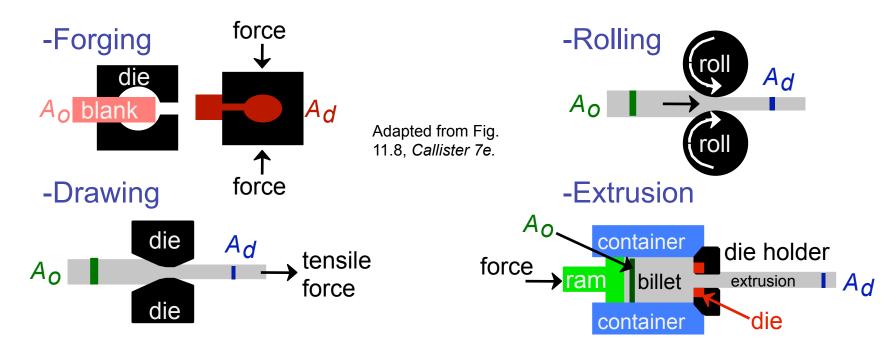
Strengthening by alloying

large impurities concentrate at dislocations on low density side



Strategies for strengthening: Cold work (%CW)

- Room temperature deformation.
- Common forming operations change the cross sectional area:



$$%CW = \frac{A_O - A_O}{A_O} \times 100$$

Impact of cold work

As cold work is increased

- Yield strength (σ_{v}) increases.
- Tensile strength (*TS*) increases.
- Ductility (%EL or %AR) decreases.

